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APPLICATION NO. FILING DATE		FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
09/970,145	10/02/2001	Nick A. Youker	279.361US1	9584	
21186	7590 04/08/20	05	EXAMINER		
SCHWEGN	MAN, LUNDBERG	PAREKH, NITIN			
P.O. BOX 29	·	ART UNIT	PAPER NUMBER		
MINNEAPC	DLIS, MN 55402		2811		
			DATE MAILED: 04/08/200	5	

Please find below and/or attached an Office communication concerning this application or proceeding.

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		Application N	0.	Applicant(s)	· E
<b></b>		09/970,145		YOUKER ET AL.	
o ffice A ction Sum	nmary	Examiner	<del>-</del>	Art Unit	
·	!	N <i>itin</i> P <b>are</b> kh		2811	
The MAILING DATE of this Period for Reply	s communication app	ears on the cov	er sheet with the	correspondence addres	is
A SHORTENED STATUTORY F THE MAILING DATE OF THIS C  - Extensions of time may be available under after SIX (6) MONTHS from the mailing dat  - If the period for reply specified above, the  - If NO period for reply is specified above, the  - Failure to reply within the set or extended p Any reply received by the Office later than t earned patent term adjustment. See 37 CF	COMMUNICATION. the provisions of 37 CFR 1.13 e of this communication. s than thirty (30) days, a reply e maximum statutory period w eriod for reply will, by statute, three months after the mailing	6(a). In no event, ho within the statutory n ill apply and will expir cause the application	wever, may a reply be tin ninimum of thirty (30) day re SIX (6) MONTHS from to become ABANDONE	mely filed  ys will be considered timely. In the mailing date of this communicip (35 U.S.C. § 133).	nication.
Status					
1) Responsive to communica	ntion(s) filed on 21 Ja	nuary 2005.			
2a)  This action is FINAL.	2b)⊠ This	action is non-fi	nal.		
3) Since this application is in	condition for allowan	ce except for f	ormal matters, pr	osecution as to the me	rits is
closed in accordance with	the practice under E	x parte Quayle	, 1935 C.D. 11, 4	53 O.G. 213.	
Disposition of Claims					
4)⊠ Claim(s) <u>7-13 and 20-25</u> is	s/are pending in the a	pplication.			
4a) Of the above claim(s)	•		eration.		
5) Claim(s) is/are allow					
6)⊠ Claim(s) <u>7-13 and 20-25</u> is	s/are rejected.				
7) Claim(s) is/are obje	cted to.				
8) Claim(s) are subject	t to restriction and/or	election requir	ement.		
Application Papers					
9)☐ The specification is objecte	ed to by the Examiner	• •			
10)⊠ The drawing(s) filed on 10-	<u>02-01</u> is/are: a)⊠ ad	ccepted or b)	objected to by the	ne Examiner.	
Appl <b>icant may not request t</b> ha	at any objection to the d	l <i>ra</i> w <i>in</i> g(s) b <b>e</b> he	d <i>in a</i> b <i>eyance. Se</i>	<b>e</b> 37 CFR 1.85( <b>a</b> ).	
R <b>e</b> pl <b>acement</b> d <b>ra</b> w <b>in</b> g sh <b>eet</b> s	s) <i>incutin</i> g the correcti	ionis required if t	hed <i>rawin</i> g(s) is oo	j <b>ecte</b> d <b>to See</b> 37 CFR 1.	121(d).
11)☐ The oath or declaration is o	bjected to by the Ex	aminer. Note th	e attached Office	Action or form PTO-1	<b>52</b> .
Priority under 35 U.S.C. § 119					
12) Acknowledgment is made of	of a claim for foreign	priority under 3	5 U.S.C. § 119(a	)-(d) or (f).	
a)	None of:				
1. Certified copies of the	ne priority documents	have been rec	eived.		
2. Certified copies of the	ne priority documents	have been rec	eived in Applicati	ion No	
3. Copies of the certific	ed copies of the priori	ity documents t	nave been receive	ed in this National Stag	je
application from the	International Bureau	(PCT Rule 17.	2(a)).		
* See the attached detailed O	ffice action for a list of	of the certified of	copies not receive	ed.	
Attachment(s)					
1) Notice of References Cited (PTO-892)		4) [	Interview Summary	(PTO-413)	
2) D Notice of Draftsperson's Patent Drawin	- , ,	_	Paper No(s)/Mail Da	ate	
<ol> <li>Information Disclosure Statement(s) (P Paper No(s)/Mail Date</li> </ol>	TO-1449 or PTO/SB/08)	· -	」Notice of Informal F ]Other:	Patent Application (PTO-152)	)
S. Patent and Trademark Office	Office Act	tion Summary		Part of Paner No (Mai	il Data 6
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#### **DETAILED ACTION**

## Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

2. Claims 7-9, 11, 12 and 20-25 are rejected under 35 U.S.C. 102(b) as being anticipated by Buckley, III, et al. (US Pat. 5477082).

Regarding claims 7, 11 and 20-25, Buckley, III, et al. disclose an electrical device (see Fig. 6) comprising:

- a flexible polyimide/tape substrate/tape automated bonding (TAB) leadframe (TABLF) substrate (see 60 in Fig. 6; Col. 3, lines 31-40; Col. 6, lines 10-13
- the TABLF including a plurality of leads/traces (see 24A/80 in Fig. 3-5), the leads/traces having a concentric generally rectangular first and second areas of the plurality of leads/traces being internally routed (see an inner area in Fig. 5; Col. 3, line 56) and configured into a generally rectangular inner lead bonding (ILB) area/portion and an outer lead bonding (OLB) area/portion (not numerically referenced in Fig. 6- see external electrodes 54 being connected to lead pads in Fig. 6; Col. 6, lines 28-31), the OLB portion having an array of external electrodes/solder balls (see 54 in Fig. 6)

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- an integrated circuit (IC) chip/die having bonding pads/input-output (I/O) connections at a perimeter of the chip (see 56 and 64 in Fig. 3, 4 and 6) being connected to an exposed portion of the leads pads/leads in the ILB portion (see Fig. 4 and 6)
- the first area of the plurality of leads/traces in the ILB portion being dimensioned to directly connect respective plurality of leads/traces to the perimeter bonding pads/I-O pads (see 64 in Fig. 4; Col. 3, line 57) of the IC chip, and
- the IC chip being connected to a printed circuit card/board (PCB) by the TABLF through the lead pads/leads in the OLB portion (see the connection 50/54 in Fig.
   6)

(Fig. 6; Fig. 3-7; Col. 3-7).

Buckley, III, et al. further disclose a second IC chip/electrical component having a smaller area than that of the IC chip (see 94 in Fig. 7) being mounted above/below a surface of the IC chip and electrically connected to the IC chip via respective lead pads/leads, which extend outward from the second IC chip/electrical component to the perimeter bonding pads/I/O pads IC chip (see connections between 94 and 56 through 24A in Fig. 7, 6 and 3; Col. 7, lines 55-67).

Regarding claims 8, 9 and 12, Buckley, III, et al. disclose the entire claimed structure as applied to claims 7 and 11 above, wherein Buckley, III, et al. further disclose the TABLF

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having a multichip module (MCM- see Fig. 6 and 7) configuration wherein two or more electrical components/chips (see 58A, 90, etc. in Fig. 6 and 7) are mounted above the IC chip (see 56 in Fig. 6) and each being electrically connected to the IC chip via respective leads/traces which extend from each of the electrical components to perimeter bonding pads/I/O pads of the IC chip (Fig. 6 and 7; Col. 7, lines 55- 67).

### Claim Rejections - 35 USC § 103

- 3. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
  - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 4. Claims 10 and 13 are rejected under 35 U.S.C. 103(a) as being unpatentable over Buckley, III, et al. (US Pat. 5477082) in view of admitted prior art (APA).

Regarding claims 10 and 13, Buckley, III, et al. teach substantially the entire claimed structure as applied to claims 7 and 11 above, except the IC chip being adapted to monitor, regulate and control delivery of electrical impulses to a heart and the electrical device is dimensioned to be implantable within a body.

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The APA teaches using conventional TABLF devices being adapted to monitor, regulate and control delivery of electrical impulses to a heart and the electrical device being implantable within a body (see specification pages 1 and 2). Furthermore, determination of parameters including dimensions such as length/width, size, etc., and weight of a TAB device in chip packaging and interconnection technology art is a subject of routine experimentation and optimization to achieve the desired effect/result for particular applications including medical, military, communication, etc.

It would have been obvious to a person of ordinary skill in the art at the time invention was made to incorporate the IC chip being adapted to monitor, regulate and control delivery of electrical impulses to a heart and the electrical device is dimensioned to be implantable within a body as taught by the APA so that the desired benefits and reliability of the device for the medical application can be achieved in Buckley, III, et al's TABLF.

### Response to Arguments

5. Applicant's arguments with respect to claims 7-13 and 20-25 have been considered but are moot in view of the new ground(s) of rejection.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Nitin Parekh whose telephone number is 571-272-1663. The examiner can normally be reached on 09:00AM-05:30PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Eddie Lee can be reached on 571-272-1732. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9318.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is 703-308-0956.

NP

04-06-05

**NITIN PAREKH** 

Nitin Parekh

PRIMARY EXAMINER

**Technology Center 2800**